# 2SB1502

### Silicon PNP epitaxial planar type Darlington

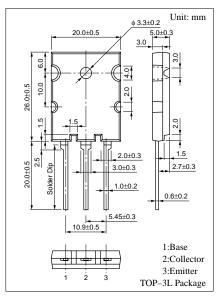
For power amplification Complementary to 2SD2275

#### Features

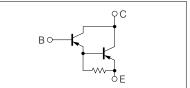
- Optimum for 55W HiFi output
- High foward current transfer ratio  $h_{FE}$ : 5000 to 30000
- Low collector to emitter saturation voltage V<sub>CE(sat)</sub>: < 2.5V

<b>5</b> ( c )						
Parameter		Symbol	Ratings	Unit		
Collector to base voltage		V <sub>CBO</sub>	-120	V		
Collector to emitter voltage		V <sub>CEO</sub>	-100	V		
Emitter to base voltage		V <sub>EBO</sub>	-5	V		
Peak collector current		I <sub>CP</sub>	-8	А		
Collector current		I <sub>C</sub>	-5	А		
Collector power	T <sub>C</sub> =25°C	D	60	117		
dissipation	Ta=25°C	P <sub>C</sub>	3.5	W		
Junction temperature		Tj	150	°C		
Storage temperature		T <sub>stg</sub>	-55 to +150	°C		

#### Absolute Maximum Ratings $(T_c=25^{\circ}C)$



#### Internal Connection

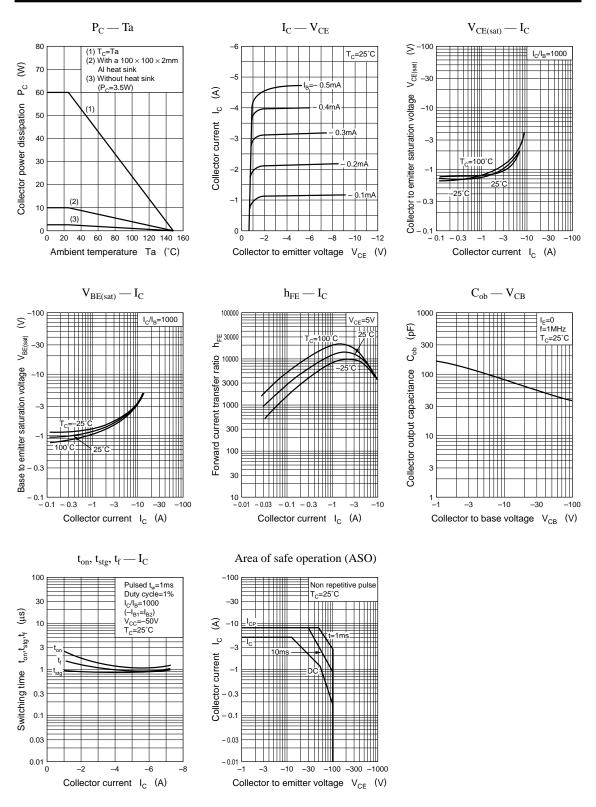


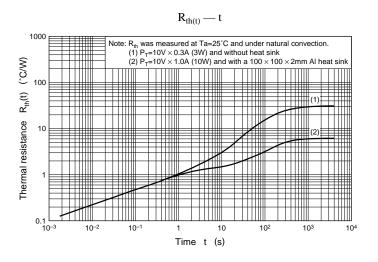
#### Electrical Characteristics $(T_C=25^{\circ}C)$

Parameter	Symbol	Conditions min		typ	max	Unit
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = -120V, I_E = 0$			-100	μA
	I <sub>CEO</sub>	$V_{CE} = -100V, I_B = 0$			-100	μA
Emitter cutoff current	I <sub>EBO</sub>	$V_{EB} = -5V, I_{C} = 0$			-100	μA
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -30 {\rm mA}, \ I_{\rm B} = 0$	-100			V
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = -5V, I_C = -1A$	2000			
	h <sub>FE2</sub> *	$V_{CE} = -5V, I_C = -4A$	5000		30000	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -4A, I_B = -4mA$			-2.5	v
Base to emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = -4A, I_B = -4mA$			-3.0	v
Transition frequency	f <sub>T</sub>	$V_{CE} = -10V, I_{C} = -0.5A, f = 1MHz$		20		MHz
Turn-on time	t <sub>on</sub>			1.0		μs
Storage time	t <sub>stg</sub>	$I_{C} = -4A, I_{B1} = -4mA, I_{B2} = 4mA,$		0.8		μs
Fall time	t <sub>f</sub>	$V_{CC} = -50V$		1.0		μs

\*hFE2 Rank classification

Rank	Q	S	Р	
h <sub>FE2</sub>	5000 to 15000	7000 to 21000	8000 to 30000	





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